

1 5. The package as recited in claim 1, wherein said
2 first conductive bus is at a first voltage potential and said
3 second conductive bus is at a second voltage potential.

1 6. The package as recited in claim 1, further
2 comprising an integrated circuit that is mounted to said
3 housing and connected to said first and second bond pads.

1 7. An electronic package, comprising:
2 a housing that has a first bond shelf that has an edge;
3 a first bond pad located on said bond pad shelf;
4 a first conductive strip that extends along said edge
5 and onto said bond shelf.

1 8. The package as recited in claim 7, further
2 comprising a second bond pad located on said first bond
3 shelf, and a second conductive bus that is connected to said
4 second bond pad by a second conductive strip that wraps
5 around said edge and extends onto said first bond shelf.

1 9. The package as recited in claim 8, wherein said
2 first bond shelf edge includes a notch that separates said
3 first conductive strip from said second conductive strip.

1 10. The package as recited in claim 8, further
2 comprising a third bond pad that is located on a second bond
3 shelf.

1 11. The package as recited in claim 8, wherein said
2 first conductive bus is at a first voltage potential and said
3 second conductive bus is at a second voltage potential.

1 12. The package as recited in claim 7, further
2 comprising an integrated circuit that is mounted to said
3 housing and connected to said first bond pad.

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1 13. A method for assembling an electronic package,
2 comprising:
3 forming a housing which has a bond pad located on a bond
4 shelf which has an edge;
5 forming a conductive strip along the edge of the bond
6 shelf;
7 removing a portion of the conductive strip.

1 14. The method as recited in claim 13, wherein the
2 conductive strip is formed by plating a conductive material
3 onto the edge.

1 15. The method as recited in claim 13, wherein the
2 portion of the conductive material is removed by drilling a
3 portion of the bond shelf.

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1 16. The package as recited in claim 13, further
2 comprising the steps of mounting an integrated circuit to the
3 housing and connecting the integrated circuit to the bond
4 pad.

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